

Title (en)
Contact spill.

Title (de)
Kontaktstift.

Title (fr)
Fiche de contact.

Publication
EP 0234235 A1 19870902 (EN)

Application
EP 87100541 A 19870116

Priority
GB 8602310 A 19860130

Abstract (en)
The contact spill is for use in the manufacture of a backplane provided with a plated-through hole for the reception of the spill. The portion of the spill which co-operates with the plated-through hole is formed in a manner which allows the spill to experience an interference-fit with the hole. The portion is further prepared with a coating to permit the spill to be subjected to a reflow solder process and thereby make a good electrical contact with the plated-through hole.

IPC 1-7
H01R 9/09

IPC 8 full level
H01R 4/00 (2006.01); **H01R 4/02** (2006.01); **H01R 4/64** (2006.01); **H01R 12/58** (2011.01); **H05K 3/42** (2006.01)

IPC 8 main group level
H01R (2006.01)

CPC (source: EP)
H01R 12/585 (2013.01)

Citation (search report)
• [A] EP 0088582 A1 19830914 - DU PONT [US]
• [A] DE 2610537 A1 19760930 - DU PONT
• [A] US 3827004 A 19740730 - HEUVEL M, et al

Cited by
DE102010024526A1; FR2866483A1; DE19810897C1; EP0451674A1; DE19831672B4; DE3909310A1; ES2274691A1; ES2383746A1; DE102015014553A1; EP3091616A1; DE202016008607U1; US7497702B2; US7309243B2; US10729016B1

Designated contracting state (EPC)
BE DE ES FR GR IT LU NL SE

DOCDB simple family (publication)
GB 2186124 A 19870805; **GB 8602310 D0 19860305**; DK 43887 A 19870731; DK 43887 D0 19870127; EP 0234235 A1 19870902; FI 870392 A0 19870129; FI 870392 A 19870731; IE 870115 L 19870730; PT 84210 A 19870201

DOCDB simple family (application)
GB 8602310 A 19860130; DK 43887 A 19870127; EP 87100541 A 19870116; FI 870392 A 19870129; IE 11587 A 19870120; PT 8421087 A 19870128